捷多邦,专业PCB打样**\$N54AB证843**出**\$N74ABT843** 9-BIT BUS-INTERFACE D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS197D - FEBRUARY 1991 - REVISED MAY 1997

- State-of-the-Art EPIC-IIB™ BiCMOS Design
 Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW) and Shrink
 Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

description

The 'ABT843 9-bit latches are designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The nine transparent D-type latches provide true data at the outputs.

A buffered output-enable (OE) input can be used to place the nine outputs in either a normal logic state (high or low logic levels) or a high-impedance state. The outputs are also in the high-impedance state during power-up and power-down conditions. The outputs remain in the high-impedance state while the device is powered down. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

SN54ABT843...JT OR W PACKAGE SN74ABT843...DB, DW, OR NT PACKAGE (TOP VIEW)



SN54ABT843 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

OE does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT843 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT843 is characterized for operation from –40°C to 85°C.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



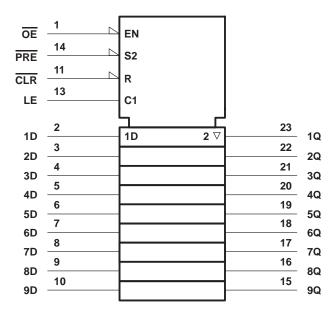


SCBS197D - FEBRUARY 1991 - REVISED MAY 1997

FUNCTION TABLE

		INPUTS			ОИТРИТ
PRE	CLR	OE	LE	D	Q
L	Х	L	Х	Χ	Н
Н	L	L	X	Χ	L
Н	Н	L	Н	L	L
Н	Н	L	Н	Н	н
Н	Н	L	L	Χ	Q ₀
Х	Χ	Н	Χ	Χ	Z

logic symbol†

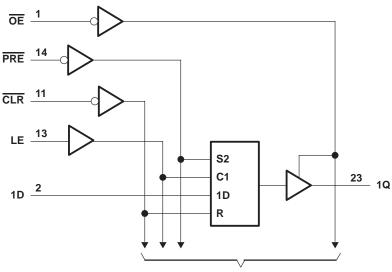


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and W packages.



SCBS197D - FEBRUARY 1991 - REVISED MAY 1997

logic diagram (positive logic)



To Eight Other Channels

Pin numbers shown are for the DB, DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high or power-off state, VO	
Current into any output in the low state, IO: SN54ABT843	96 mA
SN74ABT843	128 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{Stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

SCBS197D - FEBRUARY 1991 - REVISED MAY 1997

recommended operating conditions (see Note 3)

		SN54A	BT843	SN74ABT843		UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0	VCC	0	VCC	V
ІОН	High-level output current		-24		-32	mA
loL	Low-level output current		48		64	mA
Δt/Δν	Input transition rise or fall rate		5		5	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS			Т	A = 25°0	;	SN54ABT843		SN74ABT843		UNIT	
PARAMETER				MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5		V	
Vari	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$		3			3		3			
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$					2				v	
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$		2*					2			
Voi	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$						0.55			V	
VOL	VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$				0.55*				0.55		
V _{hys}					100						mV	
lį	$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or GND				±1		±1		±1	μΑ	
I _{OZH} ‡	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$				10		10		10	μΑ	
I _{OZL} ‡	$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$				-10		-10		-10	μΑ	
l _{off}	$V_{CC} = 0$,	V_I or $V_O \le 4.5 V$				±100				±100	μΑ	
ICEX	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 V$	Outputs high			50		50		50	μΑ	
IO§	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$		-50	-140	-180	-50	-180	-50	-180	mA	
	.,		Outputs high		1	250		250		250	μΑ	
l _{CC}	$V_{CC} = 5.5 \text{ V}, \text{ I}_{C}$ $V_{I} = V_{CC} \text{ or GI}$		Outputs low		24	34		34		34	mA	
	1 1 1 100 91 91		Outputs disabled		0.5	250		250		250	μΑ	
ΔI _{CC} ¶	V _{CC} = 5.5 V, C Other inputs at	one input at 3.4 V, VCC or GND				1.5		1.5		1.5	mA	
Ci	V _I = 2.5 V or 0.5 V			4						pF		
Co	$V_0 = 2.5 \text{ V or } 0$).5 V			7						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SCBS197D - FEBRUARY 1991 - REVISED MAY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figures 1 and 2)

			V _{CC} = 5 V, T _A = 25°C		SN54ABT843		SN74ABT843		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	
		CLR low		5.5		5.5		5.5		ns
t _W Pu	Pulse duration	PRE low		4.5		4.5		4.5		
		LE low		3.3		3.3		3.4		
	Setup time	Data before LE↓	Low	2.5		2.5		2.5		ns
,			High	3		3		3		
t _{su}		PRE inactive		1.6		1.6		1.6		115
		CLR inactive		2		2		2		
th	Hold time, data after LE↓	High Low		1		1		1		no
	⊓oiu iiiie, uata aitei LE↓			1.5†		2.3†		1.5†		ns

[†]This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT843		SN74ABT843		UNIT
	(INFO1)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	D	Q	1.2†	3.8	5.2	1.2†	7.8	1.2†	6.7†	20
^t PHL	D	Q	1.5†	3.4	6.3	1.5†	7.3	1.5†	7.2	ns
^t PLH	LE	Q	1.7†	4.4	5.6	1.7†	8.3	1.7†	7.2†	20
t _{PHL}		ζ	1.9†	4.1	6.3	1.3†	7.2	1.9†	6.9	ns
t _{PLH}		0	2.2	5	6.2	2.2	8.3	2.2	7.4	–l ns l
^t PHL	PRE	Q	2.1	4.1	6.5	2.1	7.5	2.1	7.2	
^t PLH		Q	2†	4.4	6.3	2†	7.6	2†	7.1	
^t PHL	CLR	Q	1.9†	4.5	6.8	1.9†	8.1	1.9†	8	ns
^t PZH	ŌĒ	0	1	3.4	4.5†	1	6.4	1	5.7†	
t _{PZL}		Q	2	4.3	5.7†	2	6.6	2	6.5	ns
t _{PHZ}	ŌĒ	_	2.4†	4.9	6.2	2.4†	7.3	2.4†	6.8	
t _{PLZ}		Q	1.5†	4.2	6.3	1.5†	7	1.5†	5.9†	ns

[†]This data sheet limit may vary among suppliers.

SN54ABT843, SN74ABT843 9-BIT BUS-INTERFACE D-TYPE LATCHES WITH 3-STATE OUTPUTS SCBS197D - FEBRUARY 1991 - REVISED MAY 1997

recovery-time waveform

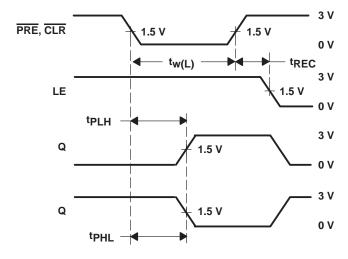
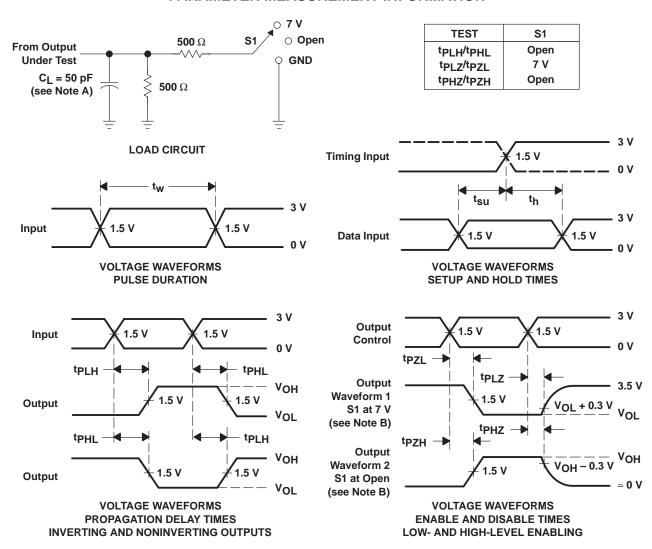


Figure 1. CLR and PRE Pulse Duration, CLR and PRE to Output Delay, and CLR and PRE to Latch-Enable Recovery Time

SCBS197D - FEBRUARY 1991 - REVISED MAY 1997

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , $t_{r} \leq$ 2.5 ns. $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated